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PATENT NUMBER

US	UTILITY	/ Patent	Application
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PATENT DATE O.I.P.E.

ART UNIT APPLICATION NO. CONT/PRIOR CLASS SUBCLASS 692 09/943196 1765 438 Charles May Arrangement and method for fabricating a semiconductor wafer

ISSUING CLASSIFICATION CROSS REFERENCE(S) **ORIGINAL** SUBCLASS (ONE SUBCLASS PER BLOCK) CLASS SUBCLASS INTERNATIONAL CLASSIFICATION Continued on Issue Slip Inside File Jacket

TERMINAL DISCLAIMER	DRAWINGS		CLAIMS ALLOWED		
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
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